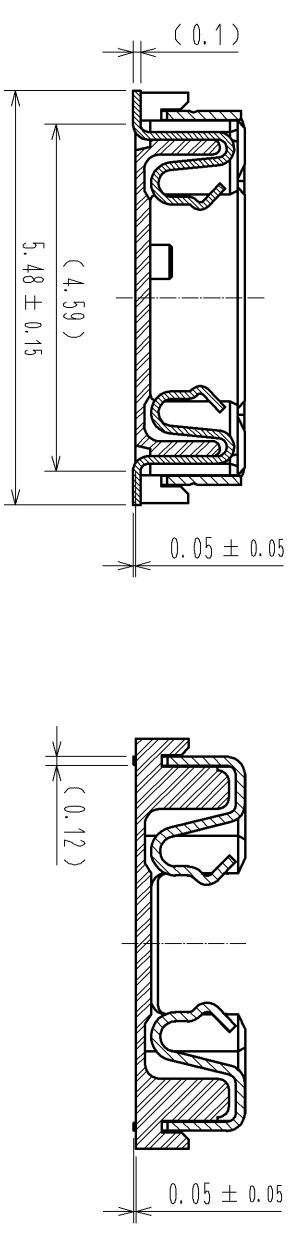


NOTE 1 All lead co-planarity shall be 0.1mm maximum.

- ② Contact plating
 - Contact area :Gold 0.05um MIN
 - SMT lead :Gold 0.05um MIN
 - Under plating:Nickel 1um MIN
- ③ Shell plating
 - All area :Gold 0.05um MIN
 - Under plating:Nickel 1um MIN 2um MAX
- ④ The peeling strength of cover tape shall comply with IEC 60286-3 (JIS C0806-3).
- ⑤ Embossed carrier tape has the sprocket hole on one side.
- ⑥ Recommended land pattern is shown. Please do not arrange the via without resist in the hatching part as shown in the figure.
- ⑦ The connector dimension when the plug engages is shown.
- ⑧ Please note that it becomes impossible to use standard extraction tool (BF4-T1) when other parts are in the crossing hatching part as shown in the figure.
- ⑨ Please layout the PCB pattern and fiber alignment, considering not to overload fiber. (Please see E1AD-K0398 about connector handling precautions.)
- ⑩ Pin assignment and functions are described in the specification of BFA4M plug connector (E1AD-K0485)
- ⑪ Please see drawing EDC3-178304-10 for 10pcs packing product BF4-RX-14DS-0.5V(10).

Part No. & Code No. corresponding to the quantity

Quantity	Part No.	Code No.
500 pcs.	BF4-RX-14DS-0.5V	CL0831-0009-9-00
1,000 pcs.	BF4-RX-14DS-0.5V(01)	CL0831-0009-9-01
2,000 pcs.	BF4-RX-14DS-0.5V(02)	CL0831-0009-9-02
10 pcs.	BF4-RX-14DS-0.5V(10)	CL0831-0009-9-10
100 pcs.	BF4-RX-14DS-0.5V(11)	CL0831-0009-9-11



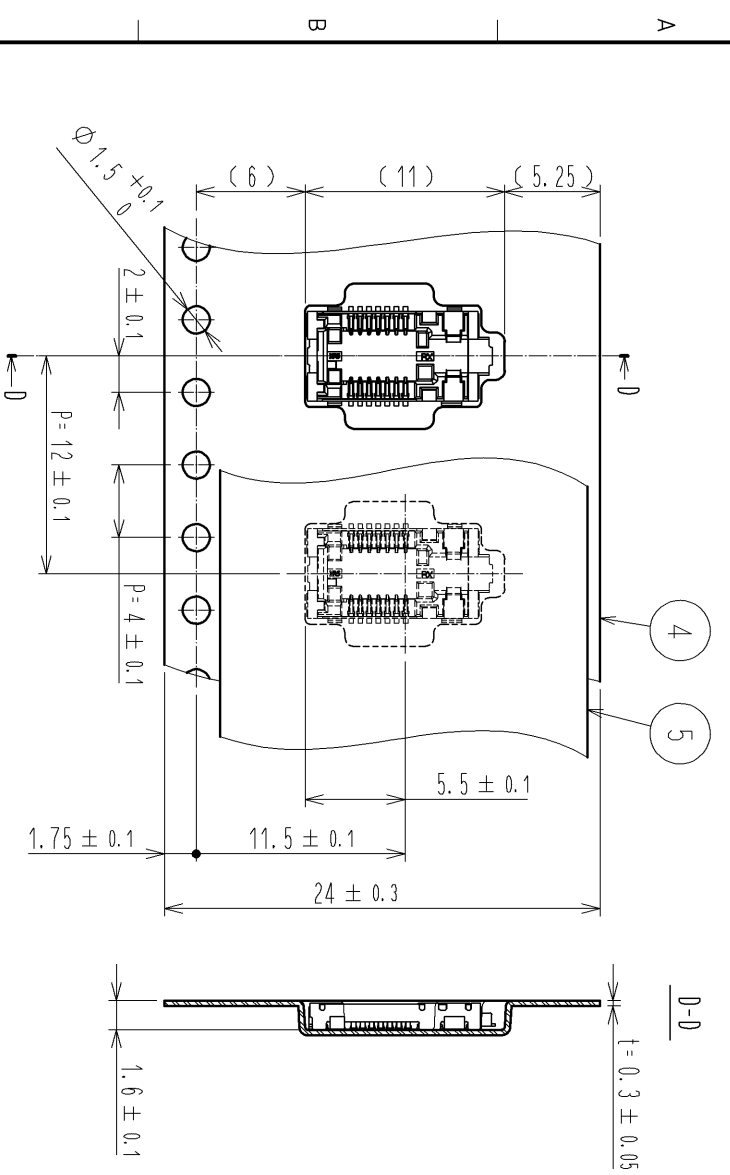
NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	Phosphor Bronze	③		6	PS		BLACK (Plastic reel)
2	Phosphor Bronze	②		5	POLYESTER		CLEAR (Cover tape)
1	LCP	UL94 V-0		4	PS		CLEAR (Embossed carrier tape)

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	10 : 1	1	DIS-K-003044	KS. JOKURA	SJ. SHIMIZU	13.08.23

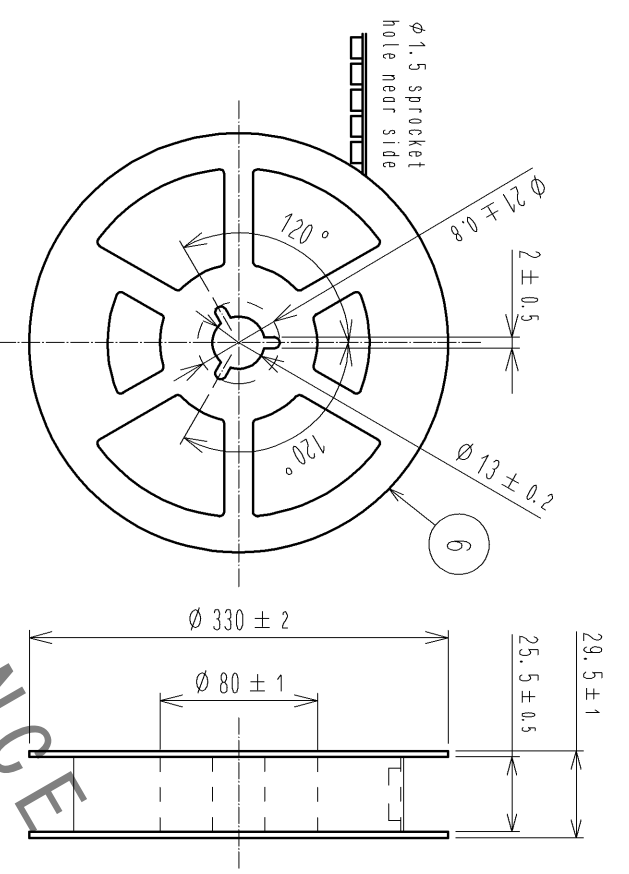
HRS
HIROSE
ELECTRIC
CO., LTD.

APPROVED	CHECKED	DESIGNED	DRAWING	PART NO.
MT. SHIBUTANI	SJ. SHIMIZU	KS. JOKURA	EDC3-178302-00	BF4-RX-14DS-0.5V(*)
12.11.15	12.11.15	12.11.15		

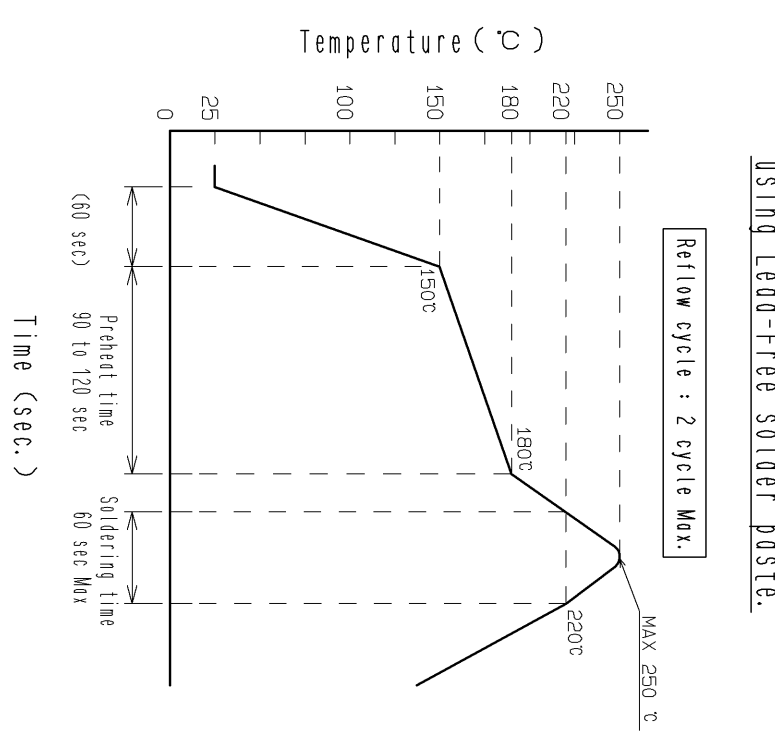
Dimensions of embossed carrier tape (Scale : FREE)



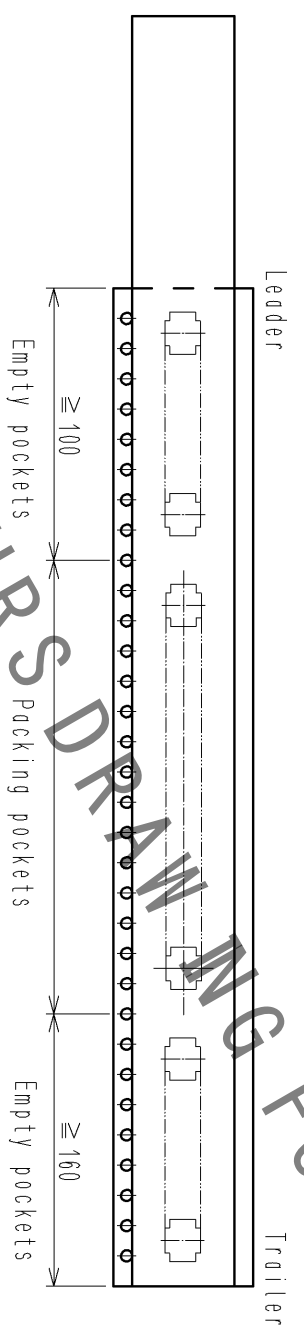
Packing reel (Scale : FREE)



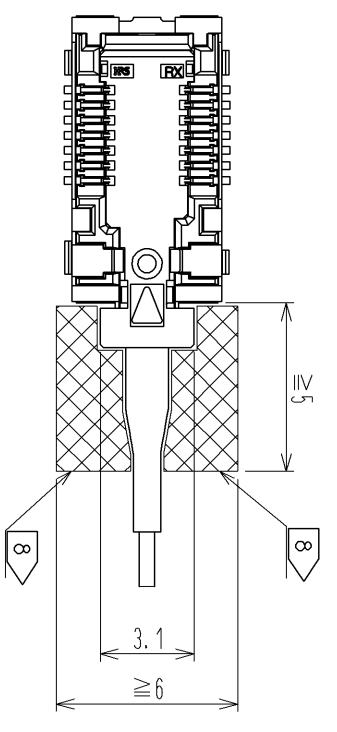
Recommended reflow temperature profile using Lead-Free solder paste.



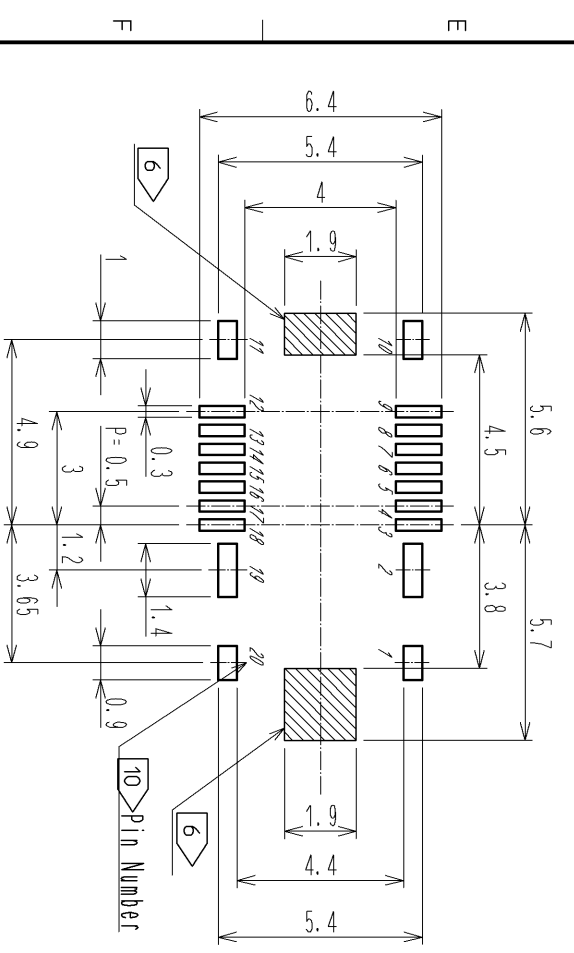
Taping direction (Scale : FREE)



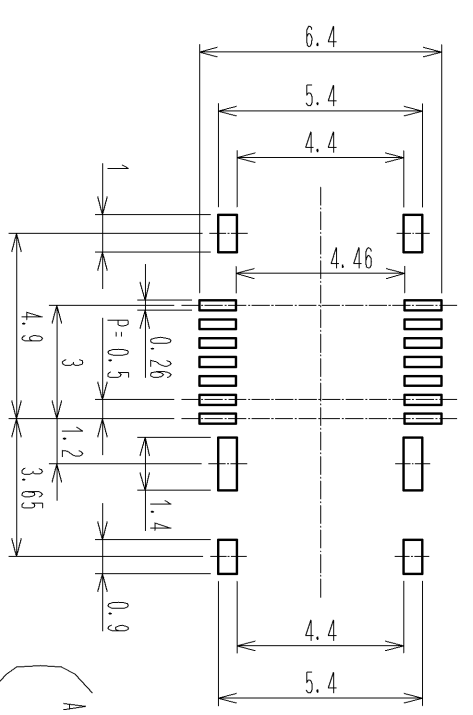
Dimensions of engaged connector (Scale:FREE)



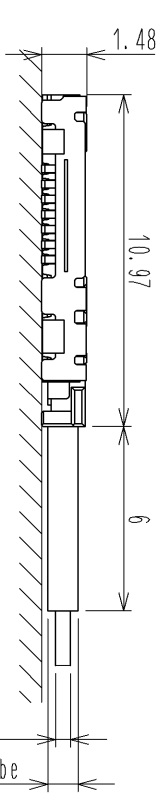
Recommended PCB land pattern



Recommended metal mask dimensions (Mask thickness : 120 μm)



Aperture ratio
 Pads mounted contacts : 70%
 Pads mounted shell : 100%



FORM HCO011-5-8

HRS

DRAWING NO.	EDC3-178302-00
PART NO.	BF4-RX-14DS-0.5V(**)
CODE NO.	